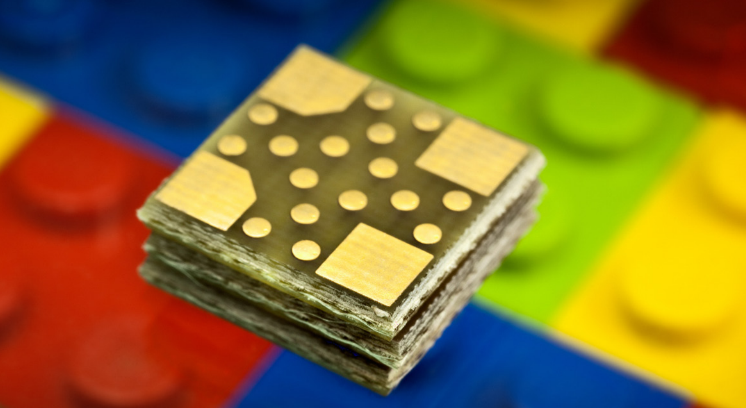

PROFILE

- The importance of electronic packaging for the semiconductor industry: New technologies and market trends
- Overview of technologies for 3D-integration
- Technologies for panel level packaging (embedding)
- Materials for RDL including material characterization (electrical and mechanical properties, aging effects, adhesion and copper diffusion)
- Assembly for bare dies, WLPs and 3D integration

New device technologies and applications with their ever increasing performance and functionality are driving the requirements and innovation for assembly and packaging. The technology boundaries between semiconductor technology, packaging and system design are becoming blurred. As a result chip, package and system designers will have to work closer together than ever before in order to drive the performance for future microelectronic systems. This tutorial will give an insight on technologies and materials within this complex topic.

REGISTRATION

www.izm.fraunhofer.de/ws_6

You will find hotels near the venue on the registration website.

PARTICIPATION FEE

480 € per person

The fees are VAT exempt according to § 4 No. 22 UStG.

VENUE

Fraunhofer Institute for Reliability and Microintegration IZM
Gustav-Meyer-Allee 25 | Bld. 17.3, Raum 60b | 13355 Berlin

CONTACT

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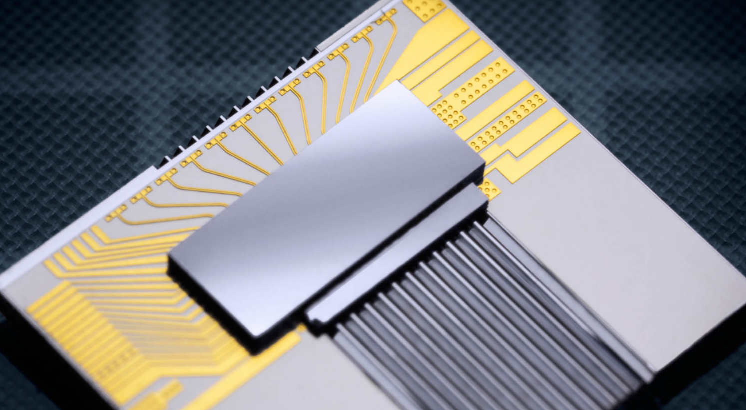
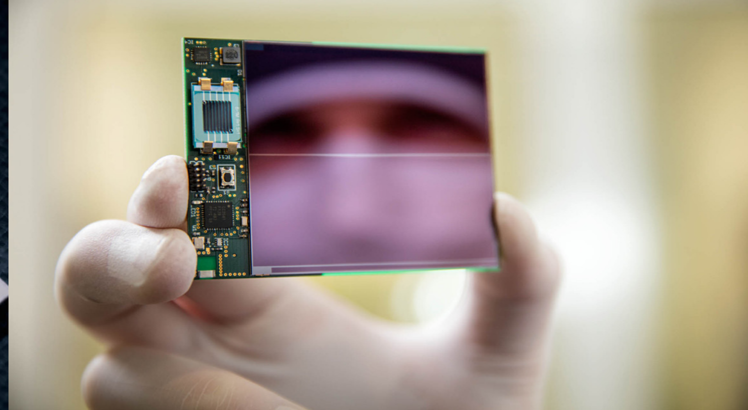
FRAUNHOFER INSTITUTE FOR
RELIABILITY AND MICROINTEGRATION IZM

NEW TRENDS AND TECHNOLOGIES IN ADVANCED PACKAGING

WORKSHOP | APRIL 19, 2018





PROGRAM

9.00 Welcome

9.30 The importance of electronic packaging for the semiconductor industry: New technologies and market trends including supply chain
Dr. Michael Töpper, Fraunhofer IZM

10.30 Coffee break

10.45 Technologies for wafer level packaging and for 3D-integration

12.00 Lunch including short lab tour

13.00 Technologies for panel lavel packaging (Embedding)

14.00 Materials for RDL including material characterization (electrical and mechanical properties, aging effects, adhesion and copper diffusion)

15.30 Coffee break

16.00 Assembly technologies for bare dies, WLPs and 3D-integration

16.30 Closing

WHO SHOULD ATTEND?

Scientists and engineers involved in advanced packaging:
Process technology, materials and equipment